
2SB1407(L)/(S)

Silicon PNP Epitaxial

HITACHI

Application

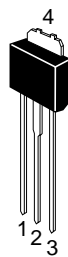
Low frequency power amplifier complementary Pair with 2SD2121(L)/(S)

Outline

DAK



S Type



L Type

- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-35	V
Collector to emitter voltage	V_{CEO}	-35	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I_C	-2.5	A
Collector peak current	$I_{C(peak)}$	-3	A
Collector power dissipation	P_C^{*1}	18	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note: 1. Value at $T_C = 25^{\circ}C$.

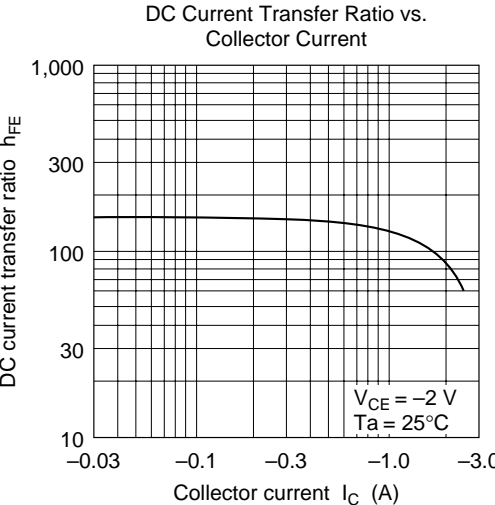
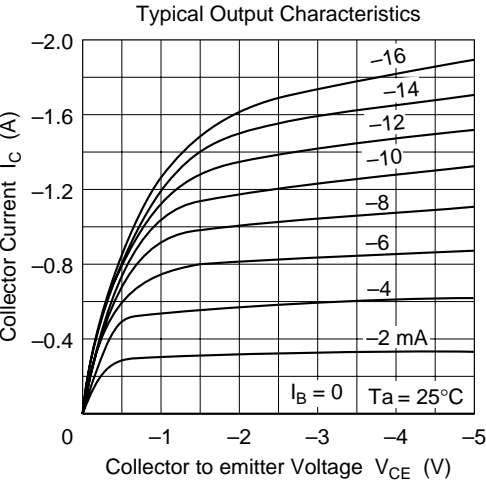
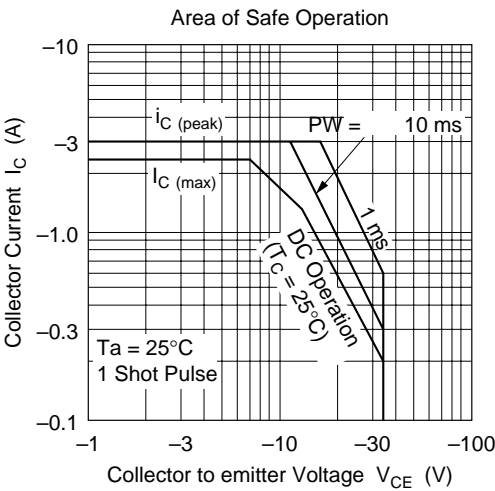
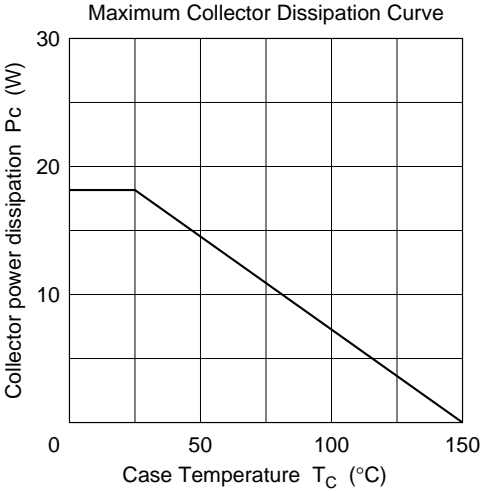
Electrical Characteristics (Ta = 25°C)

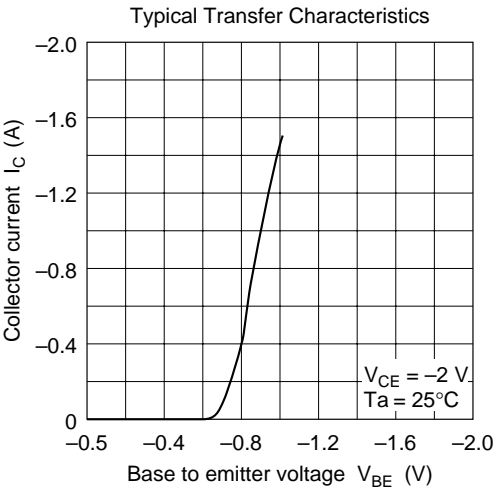
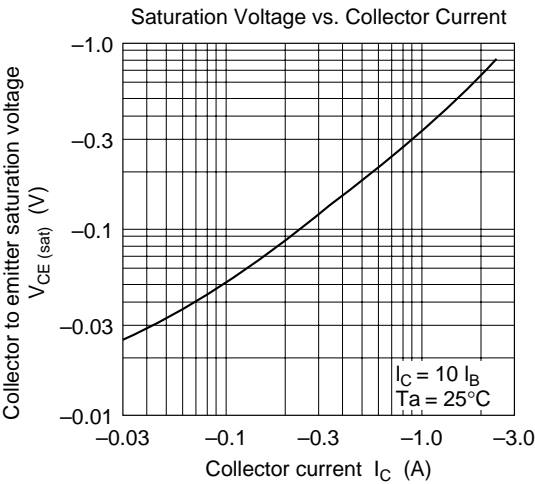
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-35	—	—	V	$I_C = -1\text{ mA}$, $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-35	—	—	V	$I_C = -10\text{ mA}$, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -1\text{ mA}$, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-20	μA	$V_{CB} = -35\text{ V}$, $I_E = 0$
DC current transfer ratio	h_{FE1}^{*1}	60	—	320		$V_{CE} = -2\text{ V}$, $I_C = -0.5\text{ A}^{*2}$
	h_{FE2}	20	—	—		$V_{CE} = -2\text{ V}$, $I_C = -1.5\text{ A}^{*2}$
Base to emitter voltage	V_{BE}	—	—	-1.5	V	$V_{CE} = -2\text{ V}$, $I_C = -1.5\text{ A}^{*2}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	-1.0	V	$I_C = -2\text{ A}$, $I_B = -0.2\text{ A}^{*2}$

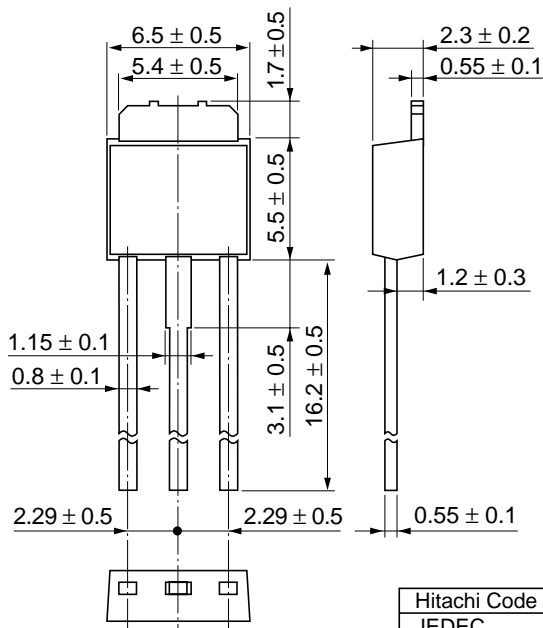
Notes: 1. The 2SB1407(L)/(S) is grouped by h_{FE1} as follows.

B	C	D
60 to 120	100 to 200	160 to 320

2. Pulse test.







Hitachi Code	DPAK (L)-(1)
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.42 g

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